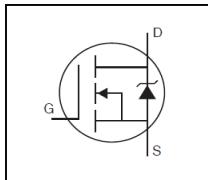


Features

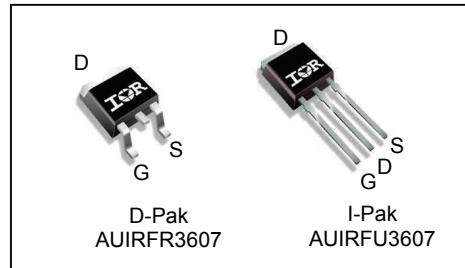
- Advanced Process Technology
- Ultra Low On-Resistance
- 175°C Operating Temperature
- Fast Switching
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified *



V_{DSS}	75V
$R_{DS(on)}$	typ. 7.34mΩ
	max. 9.0mΩ
I_D (Silicon Limited)	80A①
I_D (Package Limited)	56A

Description

Specifically designed for Automotive applications, this HEXFET® Power MOSFET utilizes the latest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of this design are a 175°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in Automotive applications and a wide variety of other applications.



G	D	S
Gate	Drain	Source

Base part number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
AUIRFU3607	I-Pak	Tube	75	AUIRFU3607
AUIRFR3607	D-Pak	Tube	75	AUIRFR3607
		Tape and Reel Left	3000	AUIRFR3607TRL

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

Symbol	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ (Silicon Limited)	80①	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ (Silicon Limited)	56①	
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ (Package Limited)	56	
I_{DM}	Pulsed Drain Current ②	310	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	140	W
	Linear Derating Factor	0.96	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy (Thermally Limited) ③	120	mJ
I_{AR}	Avalanche Current ②	46	A
E_{AR}	Repetitive Avalanche Energy ⑤	14	mJ
dv/dt	Peak Diode Recovery dv/dt ④	27	V/ns
T_J	Operating Junction and	-55 to + 175	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ⑨	—	1.045	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount) ⑧	—	50	
$R_{\theta JA}$	Junction-to-Ambient ⑧	—	110	

HEXFET® is a registered trademark of Infineon.

*Qualification standards can be found at www.infineon.com

Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	75	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.096	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 5\text{mA}$ ②
$R_{DS(\text{on})}$	Static Drain-to-Source On-Resistance	—	7.34	9.0	$\text{m}\Omega$	$V_{GS} = 10V, I_D = 46\text{A}$ ⑤
$V_{GS(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 100\mu\text{A}$
g_{fs}	Forward Trans conductance	115	—	—	S	$V_{DS} = 50V, I_D = 46\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	$V_{DS} = 75V, V_{GS} = 0V$
		—	—	250		$V_{DS} = 60V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -20V$

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

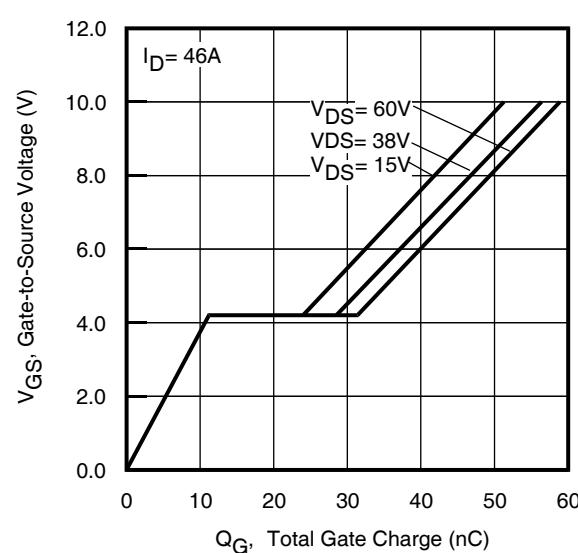
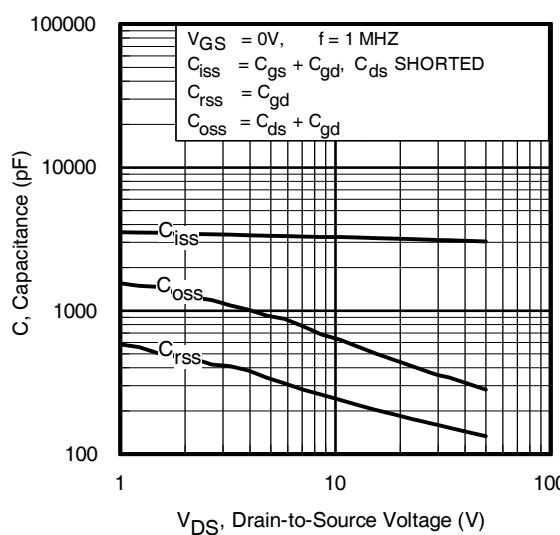
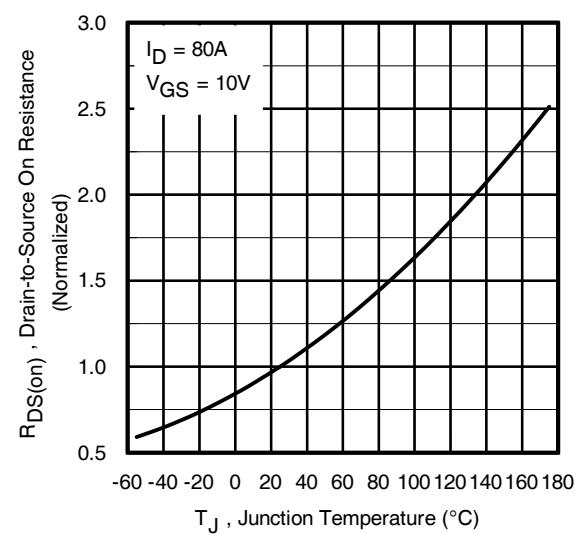
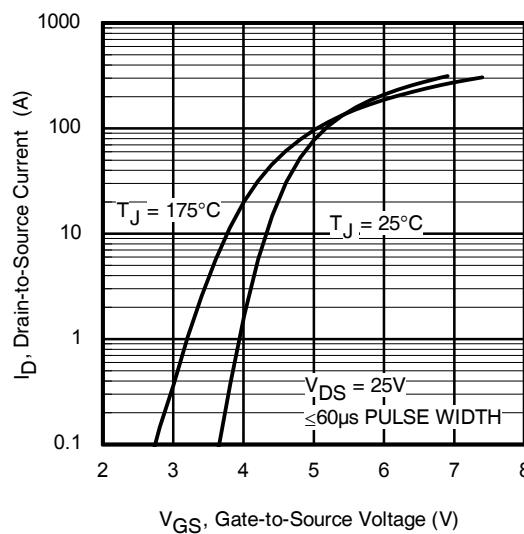
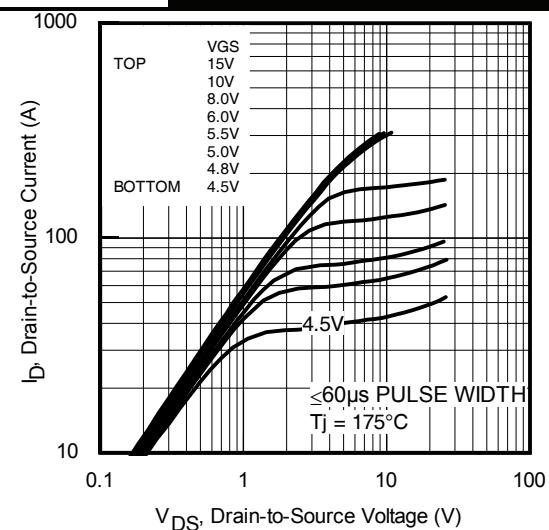
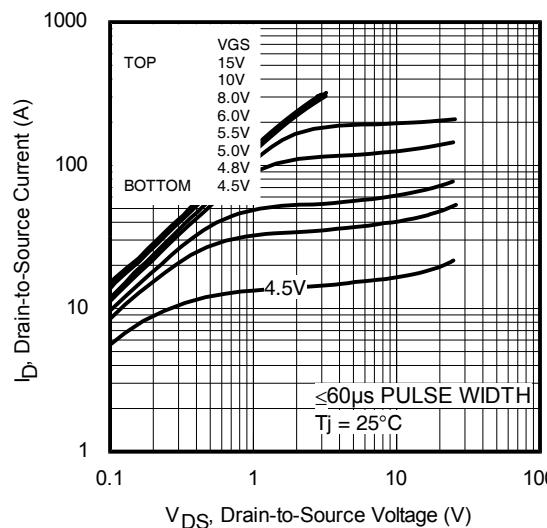
Q_g	Total Gate Charge	—	56	84	nC	$I_D = 46\text{A}$ $V_{DS} = 38V$ $V_{GS} = 10V$ ⑤
Q_{gs}	Gate-to-Source Charge	—	13	—		
Q_{gd}	Gate-to-Drain Charge	—	16	—		
Q_{sync}	Total Gate Charge Sync. ($Q_g - Q_{gd}$)	—	40	—		
R_G	Gate Resistance	—	0.55	—	Ω	
$t_{d(on)}$	Turn-On Delay Time	—	16	—	ns	$V_{DD} = 49V$ $I_D = 46\text{A}$ $R_G = 6.8\Omega$ $V_{GS} = 10V$ ⑤
t_r	Rise Time	—	110	—		
$t_{d(off)}$	Turn-Off Delay Time	—	43	—		
t_f	Fall Time	—	96	—		
C_{iss}	Input Capacitance	—	3070	—	pF	$V_{GS} = 0V$ $V_{DS} = 50V$ $f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	—	280	—		
C_{rss}	Reverse Transfer Capacitance	—	130	—		
$C_{oss \text{ eff. (ER)}}$	Effective Output Capacitance (Energy Related)	—	380	—		$V_{GS} = 0V, V_{DS} = 0V \text{ to } 60V$ ⑧
$C_{oss \text{ eff. (TR)}}$	Effective Output Capacitance (Time Related)	—	610	—		$V_{GS} = 0V, V_{DS} = 0V \text{ to } 60V$ ⑥

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_s	Continuous Source Current (Body Diode)	—	—	80①	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{sM}	Pulsed Source Current (Body Diode) ①	—	—	310		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}, I_S = 46\text{A}, V_{GS} = 0V$ ⑤
t_{rr}	Reverse Recovery Time	—	33	50	ns	$T_J = 25^\circ\text{C}$ $V_R = 64V$,
		—	39	59		$T_J = 125^\circ\text{C}$ $I_F = 46\text{A}$
Q_{rr}	Reverse Recovery Charge	—	32	48	nC	$T_J = 25^\circ\text{C}$ $di/dt = 100\text{A}/\mu\text{s}$ ⑤
		—	47	71		$T_J = 125^\circ\text{C}$
I_{RRM}	Reverse Recovery Current	—	1.9	—	A	$T_J = 25^\circ\text{C}$
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S + L_D$)				

Notes:

- ① Calculated continuous current based on maximum allowable junction temperature. Bond wire current limit is 56A. Note that current limitations arising from heating of the device leads may occur with some lead mounting arrangements.
- ② Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ③ Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.12\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 46\text{A}$, $V_{GS} = 10V$. Part not recommended for use above this value.
- ④ $I_{SD} \leq 46\text{A}$, $di/dt \leq 1920\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$.
- ⑤ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ⑥ $C_{oss \text{ eff. (TR)}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⑦ $C_{oss \text{ eff. (ER)}}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⑧ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994
- ⑨ R_θ is measured at T_J approximately 90°C .



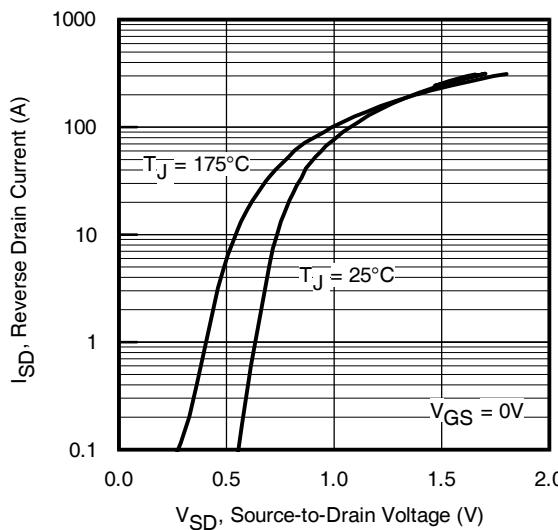


Fig. 7 Typical Source-to-Drain Diode Forward Voltage

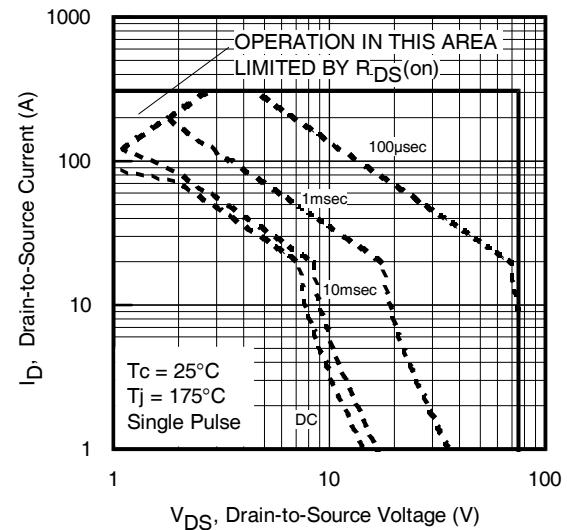


Fig 8. Maximum Safe Operating Area

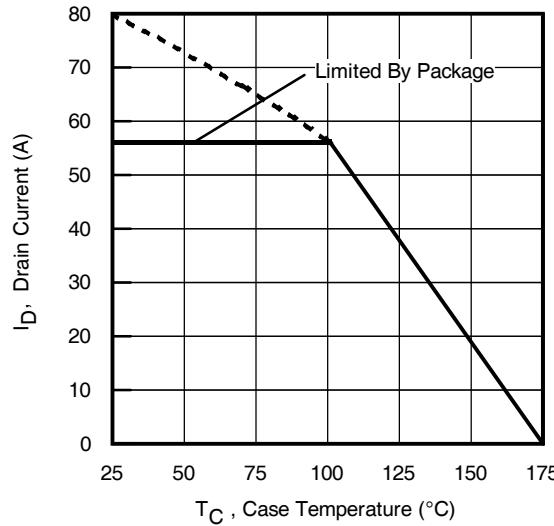


Fig. 9 Maximum Drain Current vs. Case Temperature

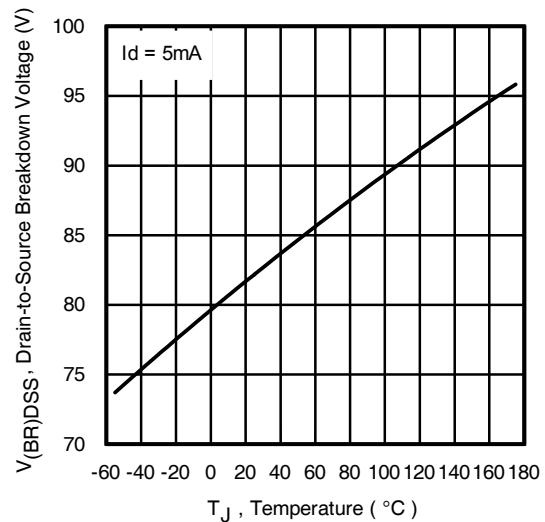


Fig 10. Drain-to-Source Breakdown Voltage

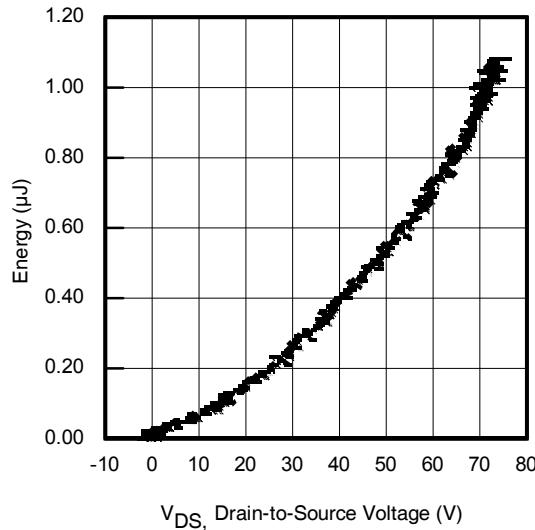


Fig. 11 Typical Coss Stored Energy

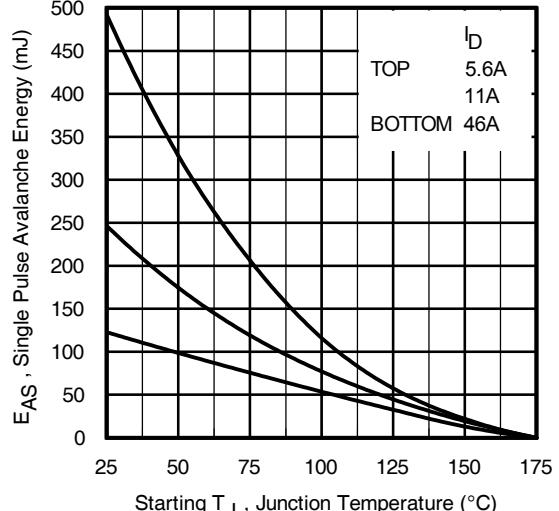


Fig 12. Maximum Avalanche Energy vs. Drain Current

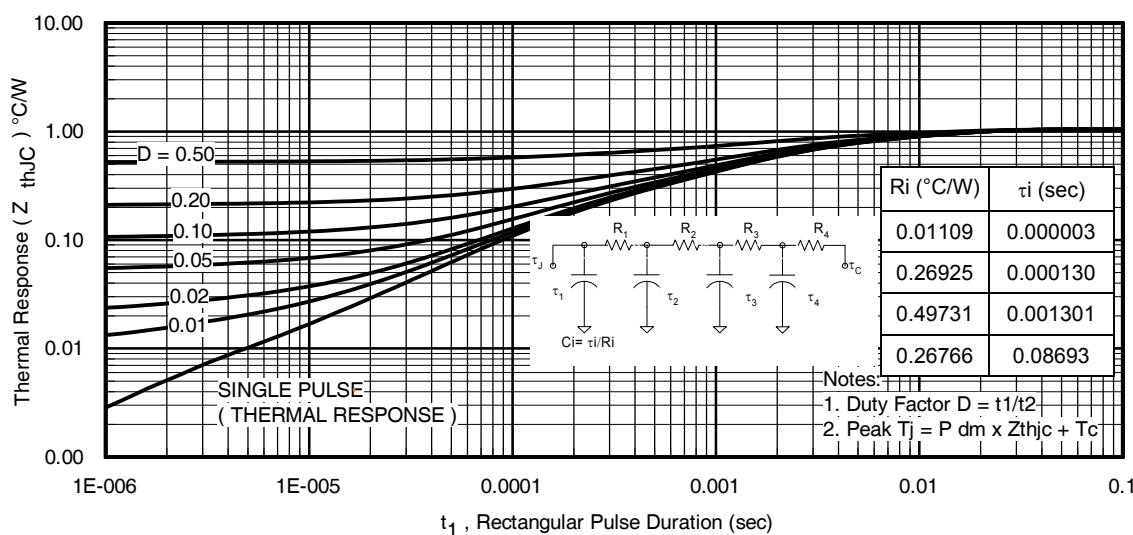


Fig 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

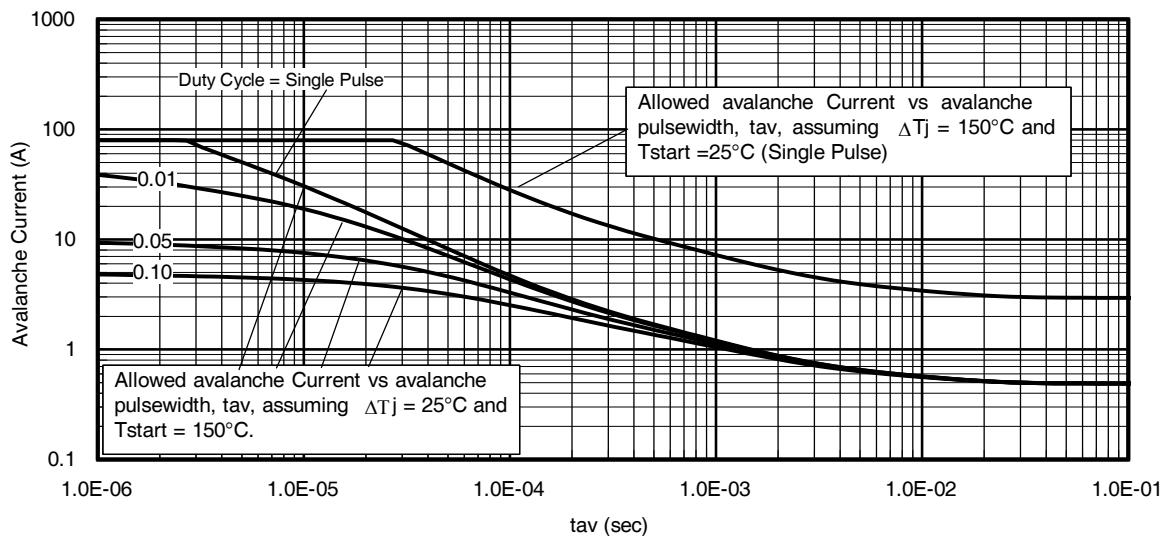


Fig 14. Typical Avalanche Current Vs. Pulse width

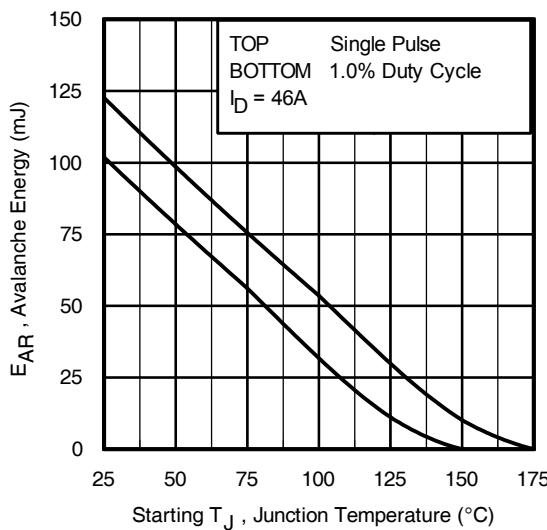


Fig 15. Maximum Avalanche Energy Vs. Temperature

Notes on Repetitive Avalanche Curves , Figures 14, 15: (For further info, see AN-1005 at www.infineon.com)

1. Avalanche failures assumption:
Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax} . This is validated for every part type.
 2. Safe operation in Avalanche is allowed as long as T_{jmax} is not exceeded.
 3. Equation below based on circuit and waveforms shown in Figures 22a, 22b.
 4. $P_{D(ave)}$ = Average power dissipation per single avalanche pulse.
 5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
 6. I_{av} = Allowable avalanche current.
 7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 13, 14).
- t_{av} = Average time in avalanche.
 D = Duty cycle in avalanche = $t_{av} \cdot f$
 $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see Figures 13)

$$P_{D(ave)} = 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$

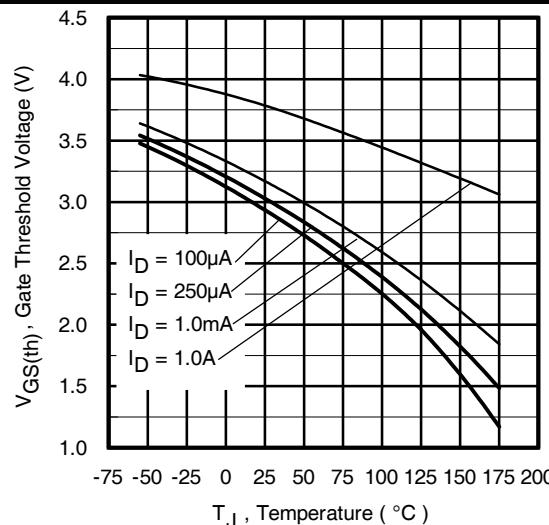


Fig. 16. Threshold Voltage vs. Temperature

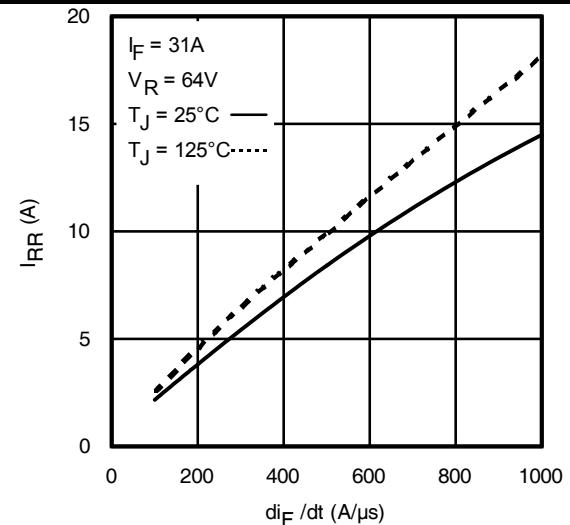


Fig. 17 - Typical Recovery Current vs. di/dt

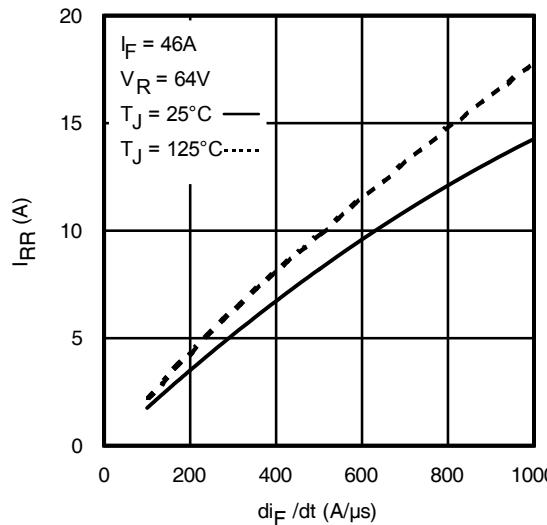


Fig. 18 - Typical Recovery Current vs. di/dt

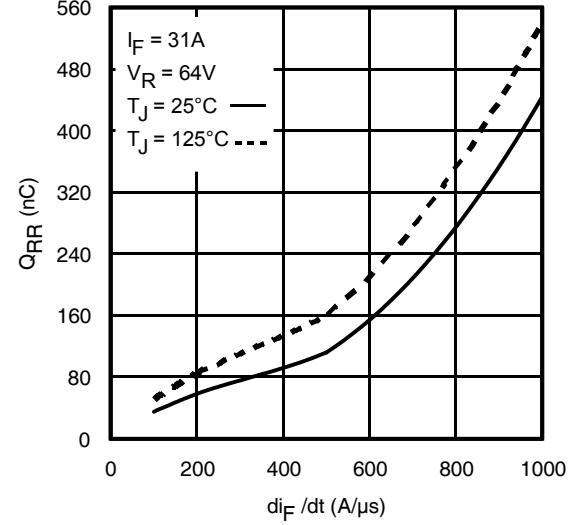


Fig. 19 - Typical Stored Charge vs. di/dt

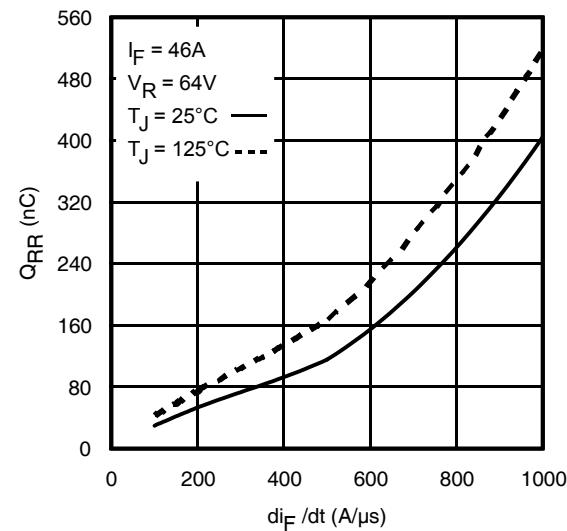


Fig. 20 - Typical Stored Charge vs. di/dt

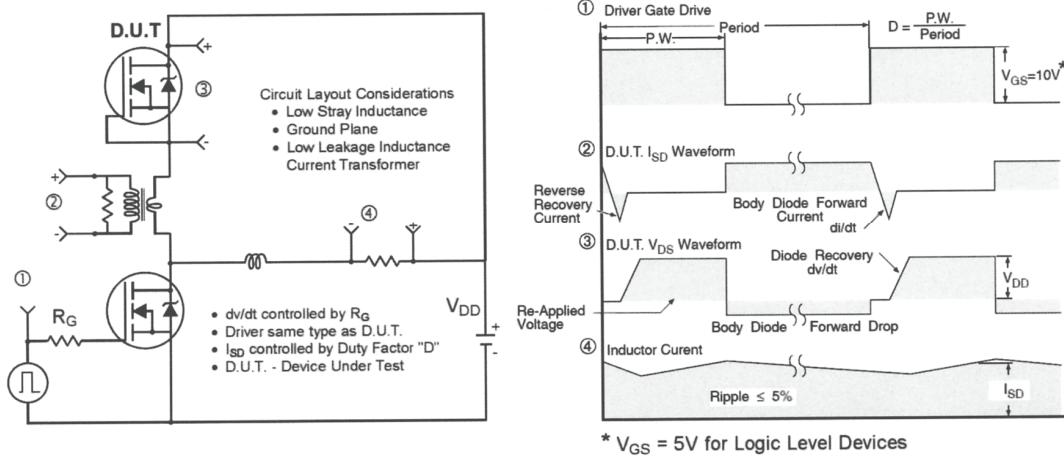


Fig 20. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

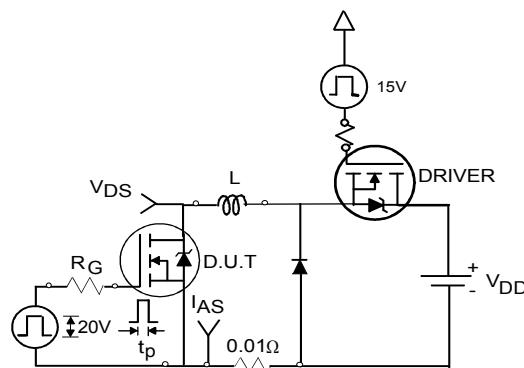


Fig 21a. Unclamped Inductive Test Circuit

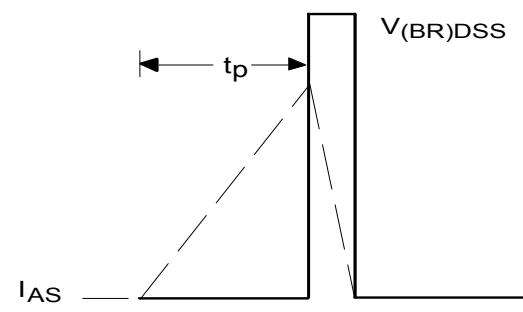


Fig 21b. Unclamped Inductive Waveforms

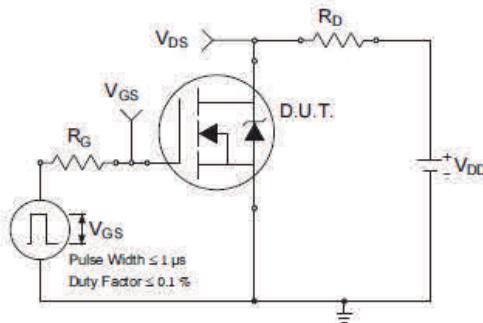


Fig 22a. Switching Time Test Circuit

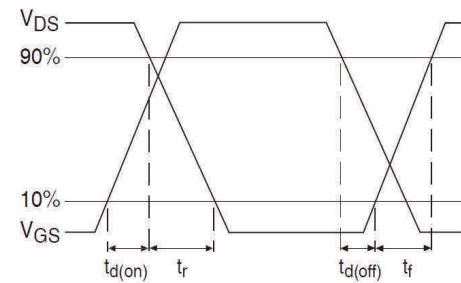


Fig 22b. Switching Time Waveforms

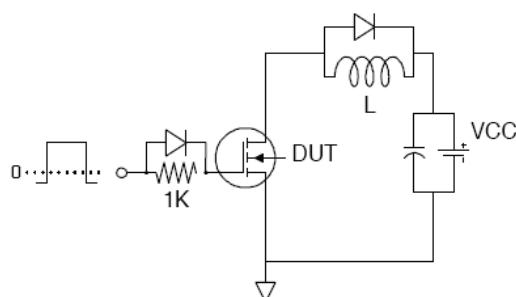


Fig 23a. Gate Charge Test Circuit

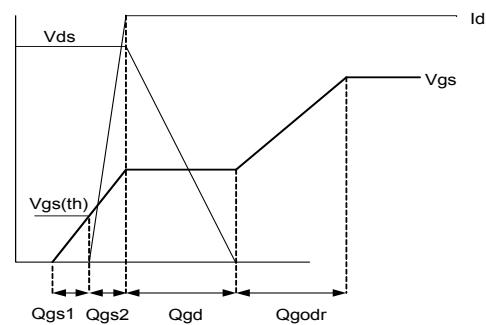
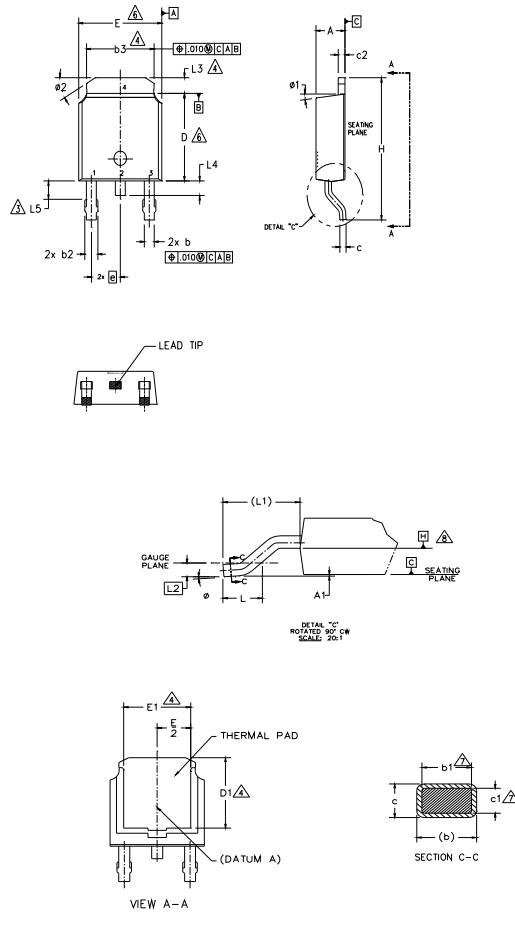


Fig 23b. Gate Charge Waveform

D-Pak (TO-252AA) Package Outline (Dimensions are shown in millimeters (inches))

NOTES:

- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
- 2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].
- 3.- LEAD DIMENSION UNCONTROLLED IN L5.
- 4.- DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- 5.- SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.
- 6.- DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [.013] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
- 7.- DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
- 8.- DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
- 9.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

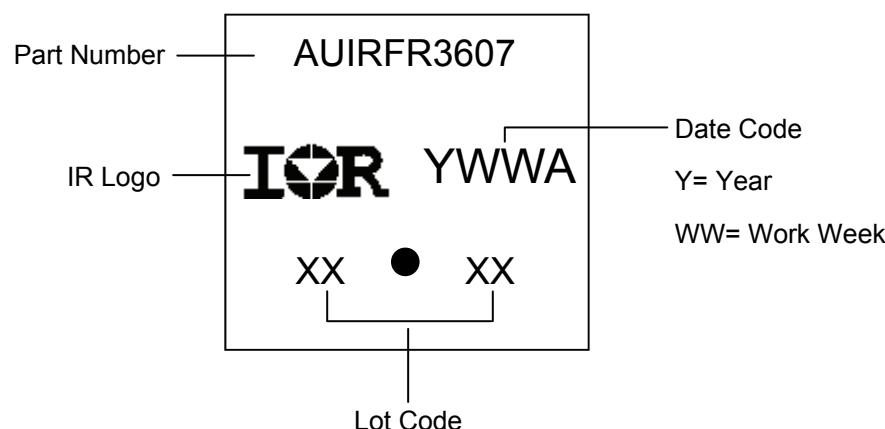
S Y M B O L	DIMENSIONS				N O T E S	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	2.18	2.39	.086	.094		
A1	—	0.13	—	.005		
b	0.64	0.89	.025	.035		
b1	0.65	0.79	.025	.031	7	
b2	0.76	1.14	.030	.045		
b3	4.95	5.46	.195	.215	4	
c	0.46	0.61	.018	.024		
c1	0.41	0.56	.016	.022	7	
c2	0.46	0.89	.018	.035		
D	5.97	6.22	.235	.245	6	
D1	5.21	—	.205	—	4	
E	6.35	6.73	.250	.265	6	
E1	4.32	—	.170	—	4	
e	2.29	BSC	.090	BSC		
H	9.40	10.41	.370	.410		
L	1.40	1.78	.055	.070		
L1	2.74	BSC	.108	REF.		
L2	0.51	BSC	.020	BSC		
L3	0.89	1.27	.035	.050	4	
L4	—	1.02	—	.040		
L5	1.14	1.52	.045	.060	3	
Ø	0°	10°	0°	10°		
Ø1	0°	15°	0°	15°		
Ø2	25°	35°	25°	35°		

LEAD ASSIGNMENTSHEXFET

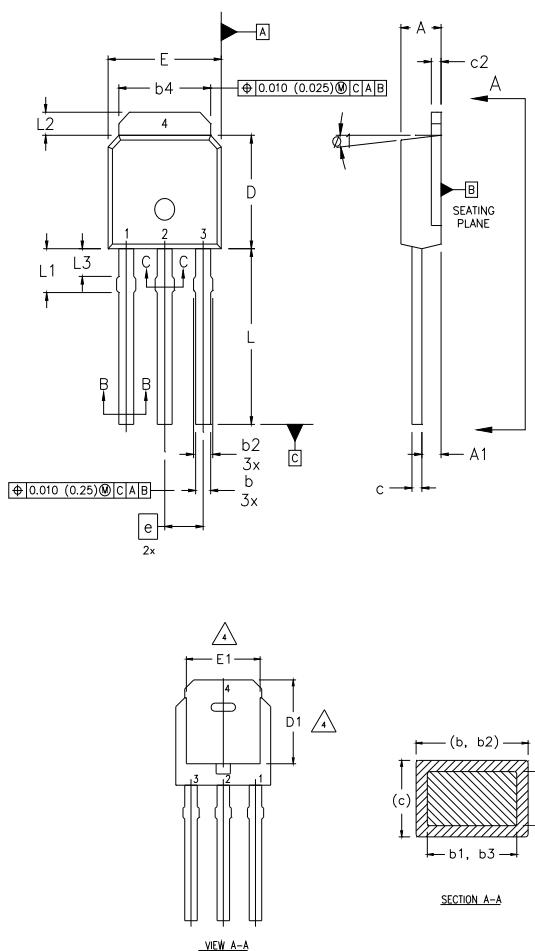
- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBT & CoPAK

- 1.- GATE
- 2.- COLLECTOR
- 3.- Emitter
- 4.- COLLECTOR

D-Pak (TO-252AA) Part Marking Information

I-Pak (TO-251AA) Package Outline (Dimensions are shown in millimeters (inches))



NOTES:

- 1 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
- 2 DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 3 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 4 THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1.
- 5 LEAD DIMENSION UNCONTROLLED IN L3.
- 6 DIMENSION b1, b3 APPLY TO BASE METAL ONLY.
- 7 OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA.
- 8 CONTROLLING DIMENSION : INCHES.

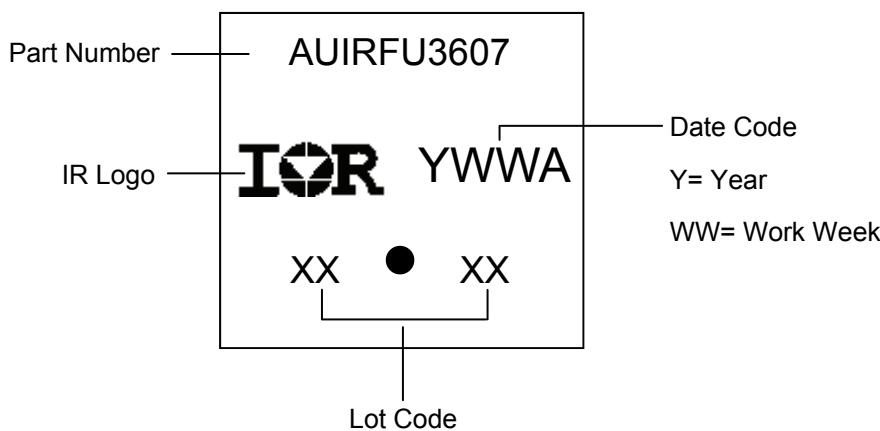
LEAD ASSIGNMENTS

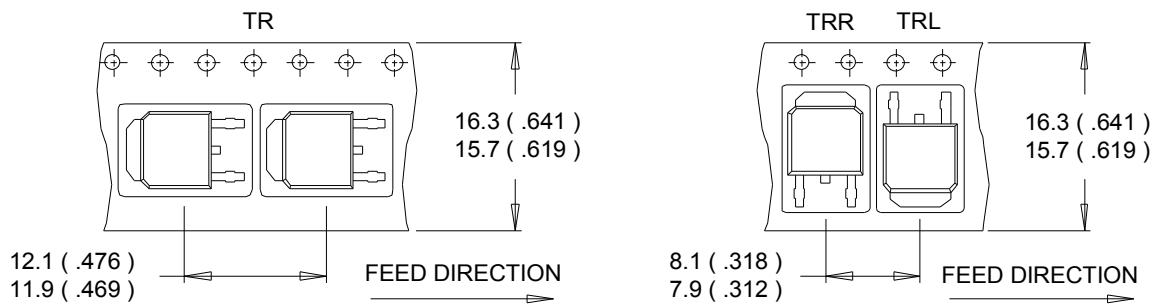
SYMBOL	DIMENSIONS				NOTES	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	2.18	2.39	0.086	.094		
A1	0.89	1.14	0.035	0.045		
b	0.64	0.89	0.025	0.035		
b1	0.64	0.79	0.025	0.031	4	
b2	0.76	1.14	0.030	0.045		
b3	0.76	1.04	0.030	0.041		
b4	5.00	5.46	0.195	0.215	4	
c	0.46	0.61	0.018	0.024		
c1	0.41	0.56	0.016	0.022		
c2	.046	0.86	0.018	0.035		
D	5.97	6.22	0.235	0.245	3, 4	
D1	5.21	—	0.205	—	4	
E	6.35	6.73	0.250	0.265	3, 4	
E1	4.32	—	0.170	—	4	
e	2.29		0.090 BSC			
L	8.89	9.60	0.350	0.380		
L1	1.91	2.29	0.075	0.090		
L2	0.89	1.27	0.035	0.050	4	
L3	1.14	1.52	0.045	0.060	5	
ø1	0°	15°	0°	15°		

HEXFET

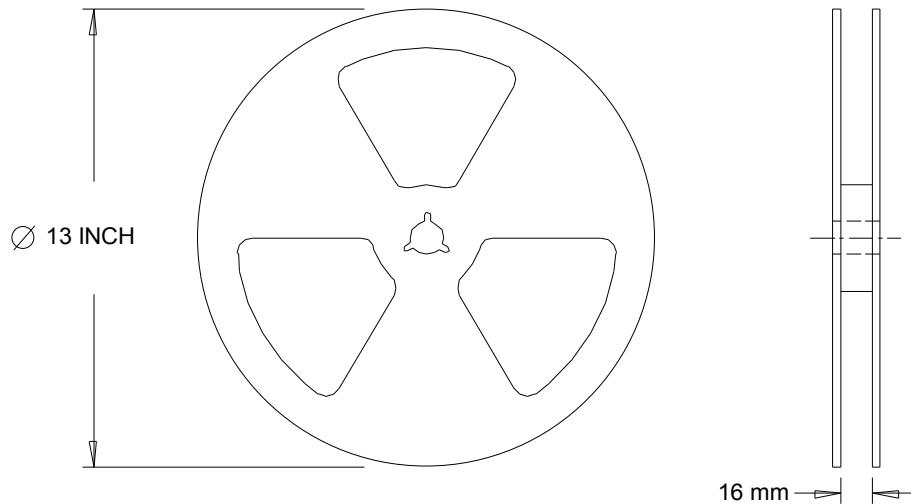
- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

I-Pak (TO-251AA) Part Marking Information



D-Pak (TO-252AA) Tape & Reel Information (Dimensions are shown in millimeters (inches))**NOTES :**

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.

**NOTES :**

1. OUTLINE CONFORMS TO EIA-481.

Qualification Information

Qualification Level		Automotive (per AEC-Q101)		
Comments: This part number(s) passed Automotive qualification. Infineon's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.				
Moisture Sensitivity Level		D-Pak	MSL1	
		I-Pak		
ESD	Machine Model	Class M4 (+/- 600V) [†] AEC-Q101-002		
	Human Body Model	Class H1C (+/- 2000V) [†] AEC-Q101-001		
	Charged Device Model	Class C4 (+/- 1000V) [†] AEC-Q101-005		
RoHS Compliant		Yes		

[†] Highest passing voltage.

Revision History

Date	Comments
10/12/2015	<ul style="list-style-type: none"> • Updated datasheet with corporate template • Corrected ordering table on page 1.
10/30/2017	<ul style="list-style-type: none"> • Corrected typo error on part marking on page 8 and 9.

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ООО "ЛайфЭлектроникс"

"LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибуторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибуторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помочь разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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